



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1803-02 Product Affected: F2932NBGP F2932NBGP8 F2933NBGP F2933NBGP8 Date Effective: 9-May-2018	DATE: 9-Apr-2018	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input type="checkbox"/> Back Mark Lot shipments will have Level 1 <input type="checkbox"/> Date Code Moisture Sensitive Label. <input checked="" type="checkbox"/> Other
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Contact: IDT PCN DESK E-mail: pcndesk@idt.com	Attachment: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: Please contact your local sales representative for sample request.
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DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology <input type="checkbox"/> Wafer Fabrication Process <input type="checkbox"/> Assembly Process <input type="checkbox"/> Equipment <input type="checkbox"/> Material <input type="checkbox"/> Testing <input type="checkbox"/> Manufacturing Site <input type="checkbox"/> Data Sheet <input checked="" type="checkbox"/> Other	<p>This notification is to advise our customers that IDT is correcting moisture sensitivity classification to MSL 1 to match what is stated in the product datasheets.</p> <p>The affected product will be shipped in antistatic bag and labeled as MSL1 according with JEDEC J-STD-020. There is no change to the assembly material sets and the peak package body temperature.</p>
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RELIABILITY/QUALIFICATION SUMMARY:

Moisture sensitive classification qual report is available on request.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A1803-02

PCN Type: Correcting Moisture Sensitivity Level matching product datasheet.

Data Sheet Change: No change to datasheet.


Detail Of Change:

This notification is to advise our customers that IDT is correcting moisture sensitivity classification to MSL 1 to match what is stated in the product datasheets.

The affected product will be shipped in antistatic bag and labeled as MSL1 according with JEDEC J-STD-020. There is no change to the assembly material sets and the peak package body temperature (remain as 260°C).

From: MSL 3 Moisture Sensitive Label
(Packing: Vacuum Dry Pack)

To: MSL 1 Not Moisture Sensitive Label
(Packing: Non Dry Pack)




CAUTION
This Bag Contains
MOISTURE-SENSITIVE DEVICES

LEVEL
3

1. Calculated shelf life in sealed bag:
12 months at < 40°C and < 90% relative humidity (RH)
2. Peak package body temperature: 260°C
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
 - a) Mounted within 168hours of factory condition <=30°C/60% RH,
 - or b) Stored per J-STD-033
4. Devices required bake, before mounting if:
 - a) Humidity indicator card reads >10% for level 2a-5a devices or >60% for level 2 devices when read at 23 +/-5 deg C
 - b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure
Bag Seal Date: _____

Note: Level and body temperature defined by IPC/JEDEC J-STD-020.




NOT MOISTURE SENSITIVE

LEVEL
1

These Devices do not require special storage conditions provided:

1. They are maintained at conditions equal to or less than 30°C/85 % RH, and
2. They are solder reflowed at a peak body temperature which does not exceed 260°C

Note: Level and body temperature defined by IPC/JEDEC J-STD-020.



Note: There is no change to the peak reflow temperature of the affected products